

Sensors and Materials

Special Issue on Sensors, Materials, and Computational Intelligence Algorithms in Robotics and AI Engineering

Call for Papers

Robotics and artificial intelligence (RAI) engineering plays an important role in not only the industrial sector but also the commercial and environmental sectors. Industry 4.0, AI, the financial sector, and many other sectors have been developed and impacted by this engineering discipline, especially AI. Many problems in engineering and industry that cannot be solved by conventional or mathematical methods can be solved by RAI. Unquestionably, the essential parts of RAI are sensors, materials, and computational intelligence. New sensors and materials will lead to a new era of development in RAI along with industrial and commercial applications, in addition to the development of new computational intelligence, and thus lead to the next generation of applications in many sectors. With this background, this special issue focuses on the new and smart development of materials, sensors, and computational intelligence in the RAI field to solve problems in the industrial, commercial, and environmental sectors. Prospective authors are invited to submit manuscripts in line with the scope and areas of focus of this special issue.

Scope:

- Smart sensors and materials in robotics and automation
- Smart IoT for robotics and AI
- Machine learning in robotics
- Nanomaterials and their applications in RAI
- Sensor fusion, sensorless applications
- Augmented/virtual reality in RAI applications
- Automation and IoT in early warning systems for the environment
- Smart microsensors and actuators in RAI
- New algorithms in computational intelligence and AI
- Neural networks, fuzzy logic, search algorithms
- New algorithms or applications in machine learning
- New deep learning technology
- Other similar topics

Submission due date: June 15, 2021

Publication date (planned): Second half of 2021

Journal website: <https://myukk.org/>

Guest Editor: Prof. Pitikhate Sooraksa (King Mongkut's Institute of Technology Ladkrabang)

Submit to: Online Manuscript Submission System (<https://myukk-org.ssl-xserver.jp/form/>)

(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors should bear the proofreading fee (JPY 10000–30000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

Editorial Department of *Sensors and Materials*

MYU K.K.

1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan

Tel: +81-3-3827-8549, Fax: +81-3-3827-8547

E-mail: myukk@myu-inc.jp

